

ABSTRACT

An object is to provide a composition for use in sintered molded bodies that enables an organic binder to be degreased in a short time without requiring
5 a special facility or step, does not cause mold deposit during molding, and suppresses cracking and swelling during molding and after sintering. In order to achieve the above-mentioned object, the present disclosure is a composition for use in sintered molded bodies containing a sinterable inorganic powder and an organic binder, wherein the organic binder contains at least a polyacetal
10 resin, a polyolefin resin and an epoxy resin, and a total end amount with respect to all polyoxymethylene units in the polyacetal resin is 0.1 mol% or more and 0.75 mol% or less.

[No figure]